

#### **Features**

- · Trench LV MOSFET Technology
- · Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note1)
- · Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

## **Maximum Ratings**

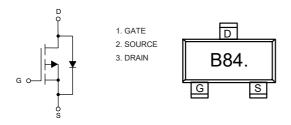
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 504°C/W Junction to Ambient (Note2)

Parameter		Symbol	Rating	Unit	
Drain-Source Voltage		V <sub>DS</sub>	-60	V	
Gate-Source Volltage		V <sub>GS</sub>	±20	V	
Continuous Drain Current	T <sub>A</sub> =25°C	1	-0.2	Α	
	T <sub>A</sub> =100°C	- I <sub>D</sub>	-0.13		
Pulsed Drain Current (Note3)		I <sub>DM</sub>	-0.8	Α	
Total Power Dissipation (Note4)		P <sub>D</sub>	0.25	W	

#### Note:

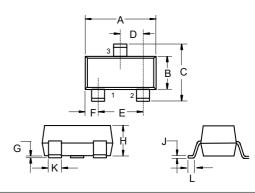
- 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 2. The value of  $R_{\theta JA}$  is measured with the device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A$  =25°C.
- 3. Repetitive rating; pulse width limited by max. junction temperature.
- 4. P<sub>D</sub> is based on max. junction temperature, using junction-ambient thermal resistance.

# **Internal Structure and Marking Code**



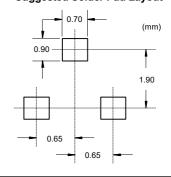
# P-Channel MOSFET





DIMENSIONS						
DIM	INC	INCHES		M	NOTE	
DIIVI	MIN	MAX	MIN	MAX	NOTE	
Α	0.071	0.087	1.80	2.20		
В	0.045	0.053	1.15	1.35		
С	0.083	0.096	2.10	2.45		
D	0.026		0.65		TYP.	
Е	0.047	0.055	1.20	1.40		
F	0.012	0.016	0.30	0.40		
G	0.000	0.004	0.00	0.10		
Н	0.035	0.044	0.90	1.10		
J	0.002	0.010	0.05	0.25		
K	0.006	0.016	0.15	0.40		
L	0.010	0.018	0.26	0.46		

#### Suggested Solder Pad Layout



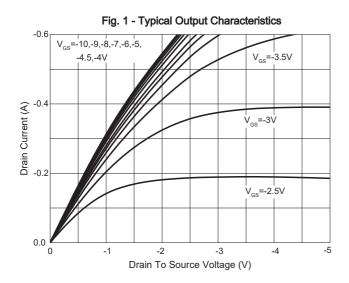


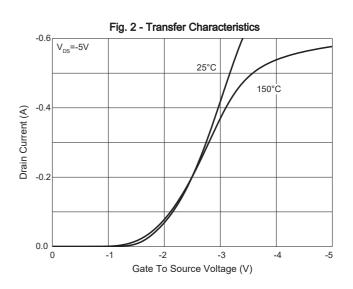
# Electrical Characteristics @ 25°C (Unless Otherwise Specified)

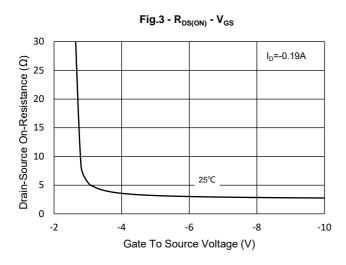
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static Characteristics							
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-60			V	
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-60V, V <sub>GS</sub> =0V			-1	μΑ	
Gate-Threshold Voltage	$V_{GS(th)}$	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.9	-1.4	-2.0	V	
Drain-Source On-Resistance	Б	V <sub>GS</sub> =-10V, I <sub>D</sub> =-0.15A		3.0	3.9	Ω	
	$R_{DS(on)}$	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-0.15A		3.5	4.6		
Gate Resistance	$R_g$	f=1 MHz, Open Drain		48		Ω	
Diode Characteristics							
Continuous Body Diode Current	Is				-0.2	Α	
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =-0.17A			-1.2	V	
Reverse Recovery Time	t <sub>rr</sub>	- I <sub>F</sub> =-0.19A,di/dt=100A/μs		20		ns	
Reverse Recovery Charge	Q <sub>rr</sub>	- 1 <sub>F</sub> 0.19Α,αι/αι-100Α/μ5		10		nC	
Dynamic Characteristics							
Input Capacitance	C <sub>iss</sub>			23			
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =-30V,V <sub>GS</sub> =0V,f=1MHz		3.4		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			1.7			
Total Gate Charge	$Q_g$			1.5			
Gate-Source Charge	$Q_{gs}$	V <sub>DS</sub> =-30V,V <sub>GS</sub> =-10V,I <sub>D</sub> =-0.19A		0.3		nC	
Gate-Drain Charge	$Q_{gd}$			0.2			
Turn-On Delay Time	t <sub>d(on)</sub>			2.3			
Turn-On Rise Time	t <sub>r</sub>	V <sub>DD</sub> =-30V, V <sub>GS</sub> =-10V,		16			
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_{G}=3\Omega, I_{D}=-0.19A$		11		ns	
Turn-Off Fall Time	t <sub>f</sub>			28			

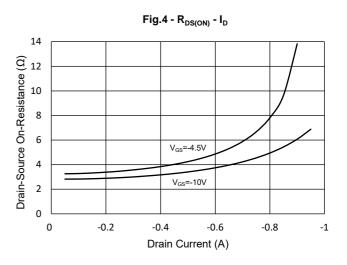


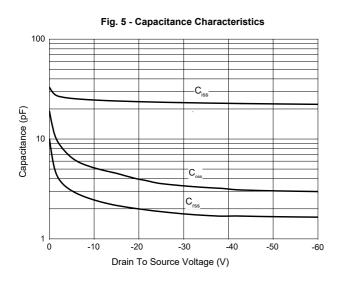
## **Curve Characteristics**

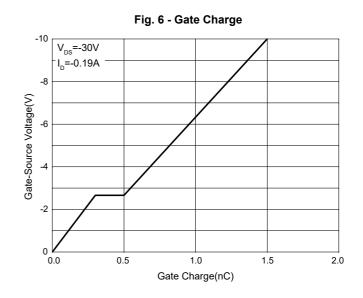






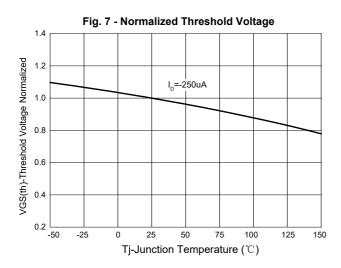


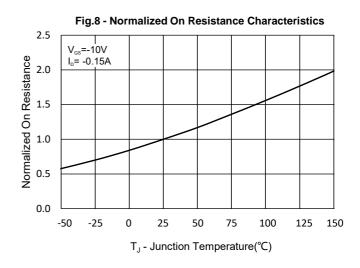


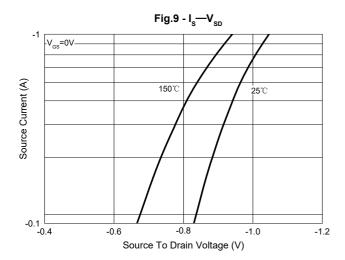




## **Curve Characteristics**







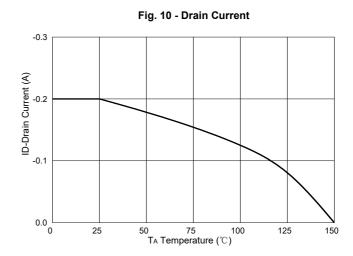
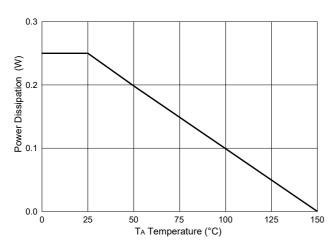
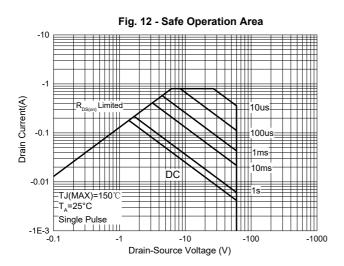


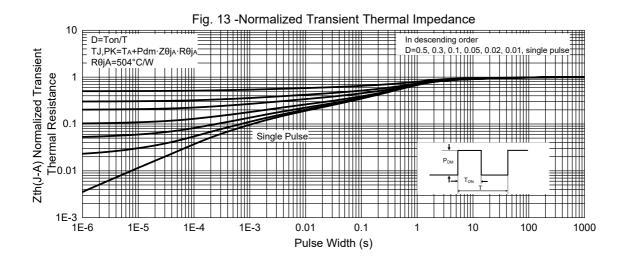
Fig.11-PD Dissipation





## **Curve Characteristics**







# **Ordering Information**

Device	Packing	
Part Number-TP	Tape&Reel:3Kpcs/Reel	

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